	COUNT	DESCRIPTION O	OF REVI	SIONS	BY	CHKD	DATE		COUN	VT	DESCF	RIPTION OF RE	VISIONS	BY	CHKI) DA	TE
^								 									
API	I DI ICAI	<u> </u> BLE STANDAF	SD .						<u> </u>								
Operating Temperature Ra				-55°C to ±105°C (Noto1) St							torage -10°C to +60°C (Not						3)
RATING		Operating Humidity Range		20% to 80% (Note 2)							corage Humidity			40% to 70% (Note3)			
		Applicable Connector									oltage 250V AC/DC					C	
		Applicable Cable		AWG#22						Curr	vont.			AWG 22 : 2A			
		Insulation Diameter		ϕ 1.2 $\sim \phi$ 1.45 mm						Curr	rent			AWG 22 . 2F			
						S	PECI	FIC	ATIC	ONS	3						
		ITEM			TES	ST ME	THOD					REQUIF	REMENT	S		QT	AT
		UCTION								1							ı
	eral Exa	mination	Visual	ally and by measuring instrument.						A	According to drawing.					0	0
Mark				Confirmed visually.													
ELE	ECTRI	CAL CHARA	CTERI	STICS	<u> </u>					-						ı	ı
Contact Resistance			20mV	20mV MAX, 1mA (DC or 1000Hz).							30 mΩ MAX.					0	_
Milli∨	olt Leve	el Method															
ME	CHAN	ICAL CHARA	CTER	ISTIC	S											1	
Mechanical Operation (Sn Plating)			30 tim	30 times insertion and extraction.							①Contact resistance: 30mΩ MAX					0	_
			g)								②No damage, crack or looseness of parts.						
Mecl	hanical (Operation	50 tim	50 times insertion and extraction.							①Contact resistance: 30mΩ MAX						_
		(Au Plating	g)								②No damage, crack or looseness of parts.					0	
Vibration			Freque	Frequency 10 to 55 Hz, single amplitude 0.75 mm,							①No electrical discontinuity of 1 μ s.						_
			_	at 10 cycles for 3 direction.							②No damage, crack or looseness of parts.					°	
Shoo	ck			Acceleration 490 m/s ² duration of pulse 11 ms at 3							·					0	_
			times	for 3 di	rection	S.											
ENI	/IDON	IMENTAL CH	IA DAC	TEDI	etice	2											
	p Heat	INILITAL OF		Exposed at 40 ± 2 °C , humidity 90 to 95 %, 96 h.							①Contact resistance: 30 mΩ MAX.						
·			•	(After leaving the room temperature for 1 to 2h.)							②No damage, crack or looseness of parts.						-
											_						
Rapid Change of			Tempe	Temperature -55 °C→ +105 °C								(1)Contact resistance: 30 mΩ MAX.					
Temperature			Time	Time 30min → 30min Under 5 Cycles								. ②No damage, crack or looseness of parts.					_
			(The t	(The transferring time of the tank is 2 to 3 MIN)													
			(After	leaving	the ro	om tem	perature	for 1	to 2h.))							
Note	: 1: Inclu : 2: No c : 3: Appl	de the temperature ondensing y to the condition idity range is appli	of long t	term sto	orage fo		-		efore p	cb on	ı board,	, after pcb boar	d , operati	ng temp	eratur	e and	
								DRAV	/N	DI	ESIGNE	D CHECK	ED A	PPROVE	D	RELEAS	SED
							J	J.S CHOI		J.S CHOI		OI S.M.L	M T.S KANG		ENG	ENG	
								17.12.22			7.12.2				20. 02. 13 DEPT		
Unles	ss otherw	vise specified, refer	0512.	17.12.22			L'			<u> </u>	· · · · · · · · · · · · · · · · · · ·		DEP	ソ			
ИОТ	E QT	: QUALIFICATION	TEST	AT: AS	SSURA	NCE TI	EST O:	APPL	ICABL	E TES							
	HIRC	SE KOREA C	O.,LTD	"LTD. SPECIFICA				TIO	N SF	HEE	T PART NO. DF51K-22SCFA (800)						
COD	E NO.(OI	_D)		DRAWING NO.					CODE NO.				1 /				1 /
CL				ELC4-611496						CL 6652-0043-1-800							